ASDM6E4D120LSX8H

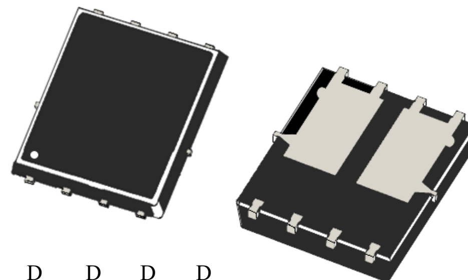
Dual N-Channel Enhancement Mode Field Effect Transistor

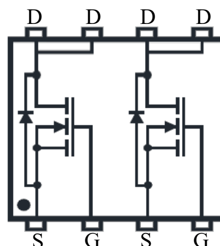
FEATURES

- · Low $R_{DS(on)}$
- · AEC-Q101 Qualified
- · Suffix "H" indicates Halogen-free parts, ex. ASDM6E4D120LSX8H

PIN CONFIGURATION

DFN5×6-8L





TOP VIEW

D	Drain
G	Gate
S	Source

Maximum Ratings(T_A =25 ℃ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	45	V
Gate-Source Voltage		V_{GS}	±20	
Continuous Drain Current	T_C=25℃	I_D	37	A
	T_C=100℃		23	
Pulsed Drain Current (Note 1)		I_{DM}	160	A
Avalanche Current		I_{AS}	12	A
Single Pulse Avalanche Energy (Note 2)		E_{AS}	36	mJ
Power Dissipation	T_C=25℃	P_D	21	W
Thermal Resistance from Junction to Ambient (Note 3)		$R_{\theta JA}$	58	℃/W
Thermal Resistance from Junction to Case		$R_{\theta JC}$	5.9	℃/W
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to + 150	℃

Note:

1. The data tested by pulsed, pulse width ≦100μs, duty cycle ≦2%, Reptitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150°C.

2. Limited by $T_{J(MAX)}$, starting T_J=25°C, L=0.5mH, R_g=25Ω, I_{AS}=12A, V_{GS}=10V.

3. Device mounted on FR-4 substrate PC board, 2oz copper, with 1 $inch^2$ copper plate in still air.

Electrical Characteristics(T_A =25 ℃ unless otherwise specified)

Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	I_D=250μA	$V_{(BR)DSS}$	45	-	-	V
Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250μA	$V_{GS(th)}$	1.2	-	2.5	V
Zero Gate Voltage Drain Current	V_{DS}=36V	I_{DSS}	-	-	1	μA
Gate Leakage Current	V_{GS}=±16V	I_{GSS}	-	-	±100	nA
Drain-Source On-Resistance	V_{GS}=10V, I_D=10A V_{GS}=4.5V, I_D=8A	$R_{DS(on)}$	- -	10.8 -	13.5 18.0	mΩ
Dynamic						
Forward Transconductance	V_{DS}=5V, I_D=5A	g_{FS}	-	14	-	S
Gate Resistance	V_{DS}=0V, V_{GS}=0V, f=1MHz	R_g	-	1.3	-	Ω
Total Gate Charge	V_{DS}=30V, V_{GS}=4.5V, I_D=10A	Q_g	-	7	-	nC
	V_{DS}=30V, V_{GS}=10V, I_D=10A		-	15	-	
Gate-Source Charge		Q_{gs}	-	3	-	
Gate-Drain Charge		Q_{gd}	-	3	-	
Input Capacitance	V_{DS}=30V, V_{GS}=0V, f=1MHz	C_{iss}	-	830	-	pF
Output Capacitance		C_{oss}	-	260	-	
Reverse Transfer Capacitance		C_{rss}	-	20	-	
Turn on Delay Time	V_{DD}=30V, I_D=10A V_{GS}=10V, R_g=4.7Ω	$t_{d(on)}$	-	10	-	ns
Turn on Rise Time		t_r	-	16	-	
Turn off Delay Time		$t_{d(off)}$	-	9	-	
Turn off Fall Time		t_f	-	2	-	
Drain-Source Body Diode						
Diode Forward Voltage	V_{GS}=0V, I_S=1A	V_{SD}	-	-	1.2	V
Diode Continuous Forward Current	-	I_S	-	-	37	A
Diode Pulse Current		I_{SM}	-	-	160	A
Reverse Recovery Time	I_S=10A, di/dt=100A/μs	t_{rr}	-	17	-	ns
Reverse Recovery Charge		Q_{rr}	-	7	-	nC

RATINGS AND CHARACTERISTIC CURVES

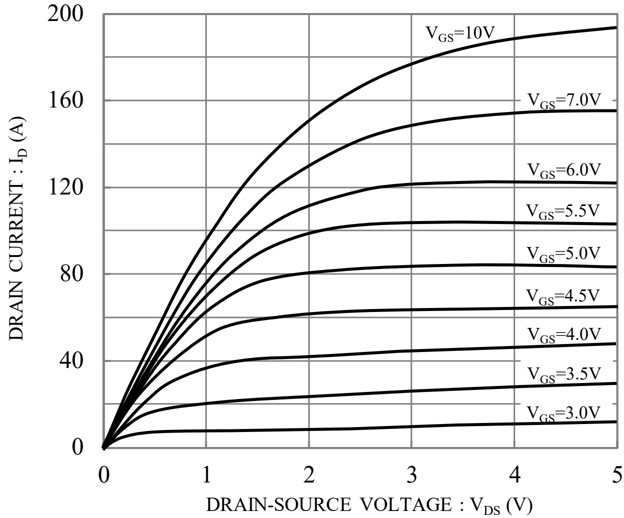


Fig.1 Typical Output Characteristics

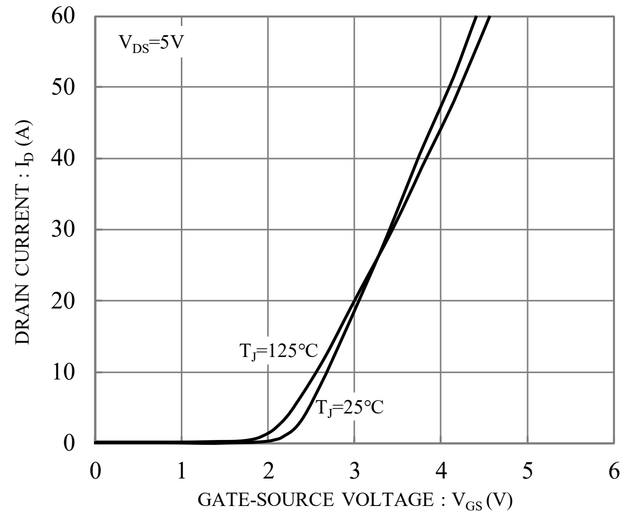


Fig.2 Typical Transfer Characteristics

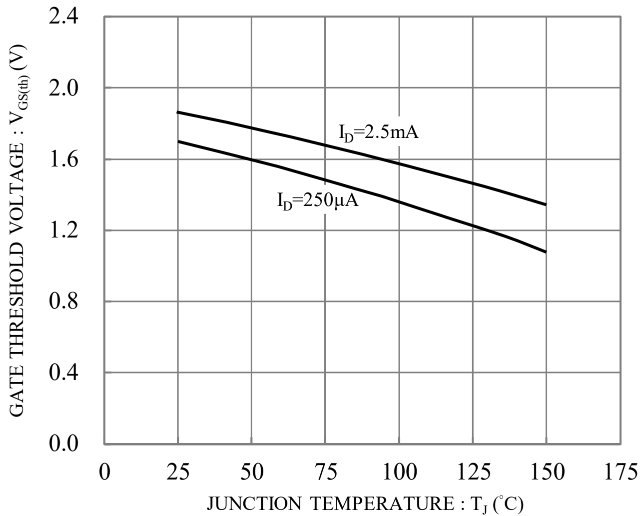


Fig.3 Gate Threshold Voltage vs. Junction Temperature

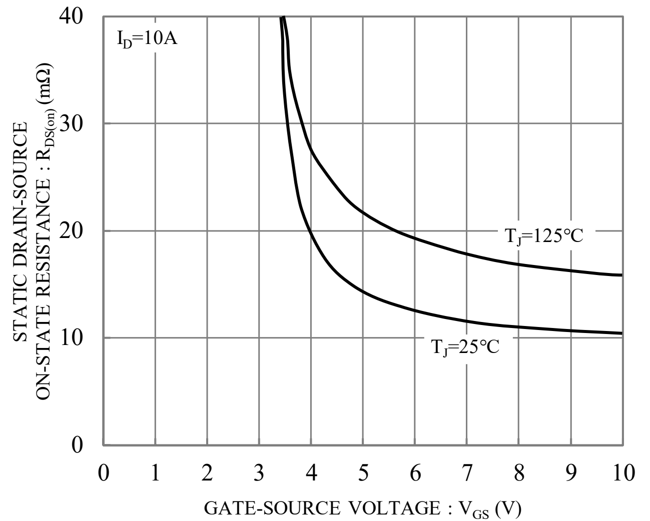


Fig.4 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

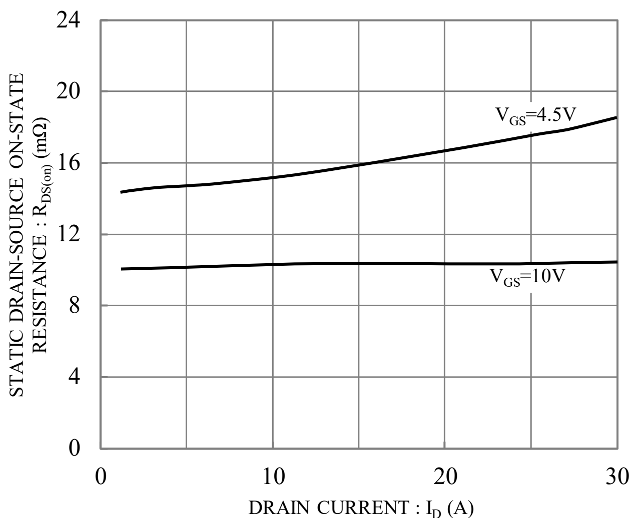


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

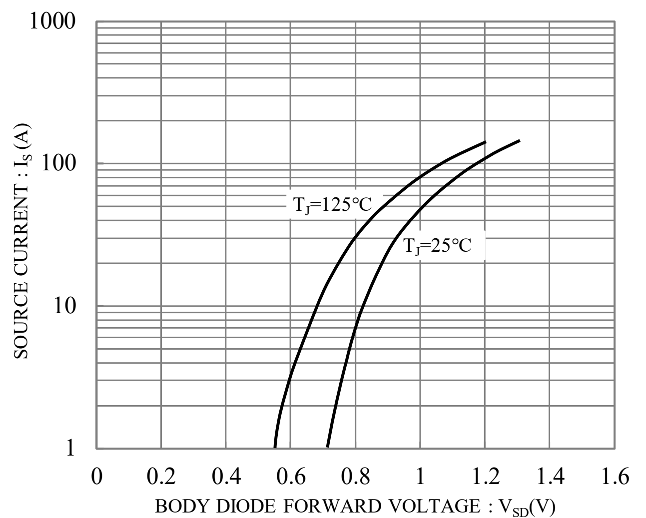


Fig.6 Body Diode Forward Voltage vs. Source Current

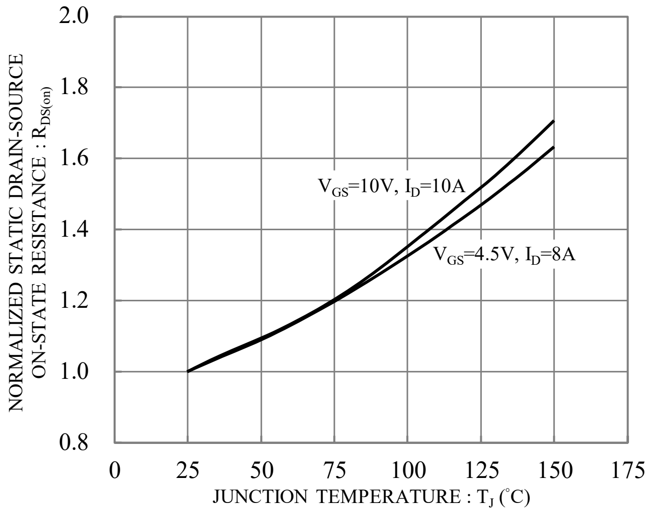


Fig.7 Drain-Source On-State Resistance vs Junction Tempearture

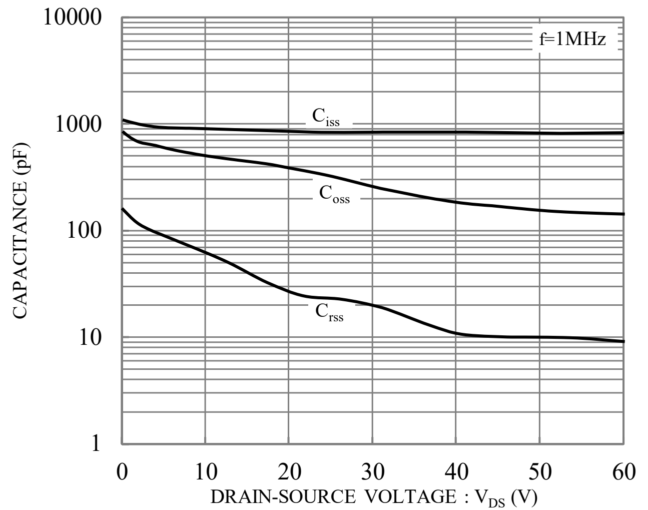


Fig.8 Capacitance vs Drain-Source Voltage

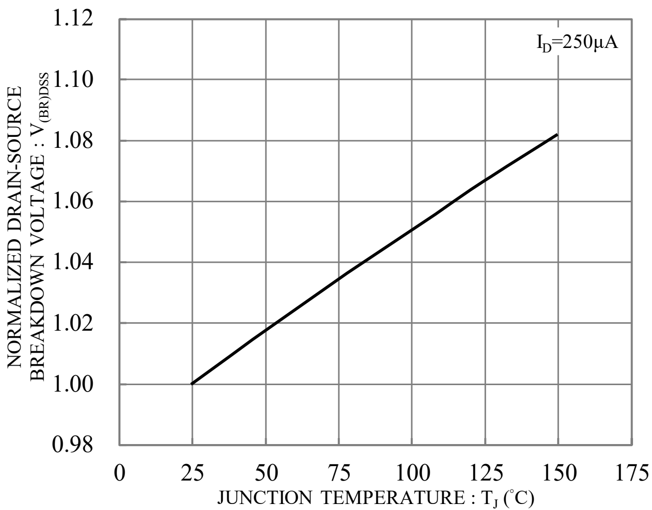


Fig.9 Breakdown Voltage vs Junction Temperature

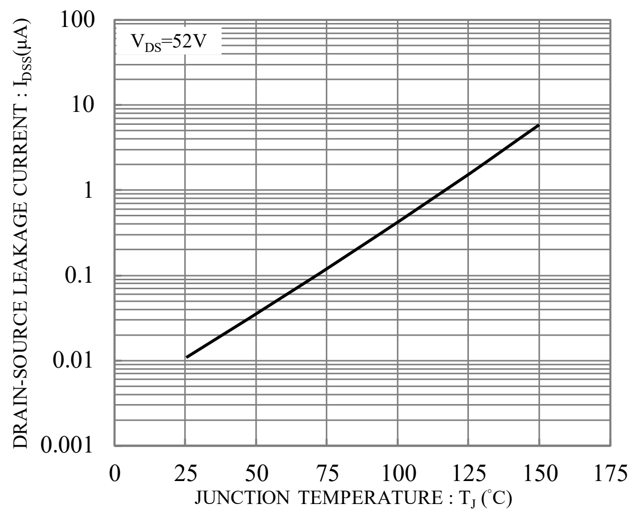


Fig.10 Drain-Source Leakge Current vs Junction Temperature

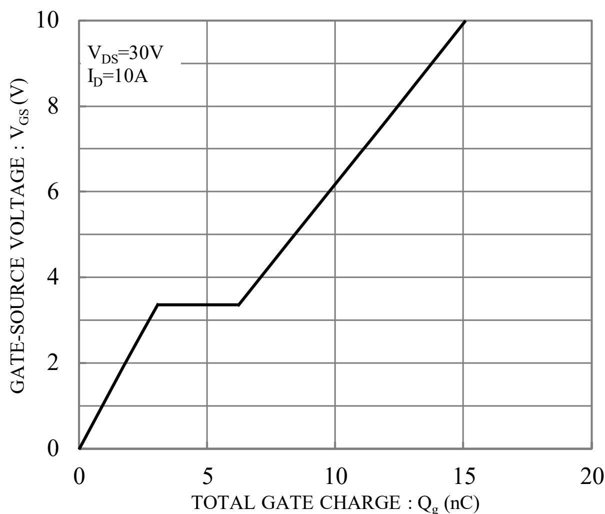


Fig.11 Gate Charge Characteristics

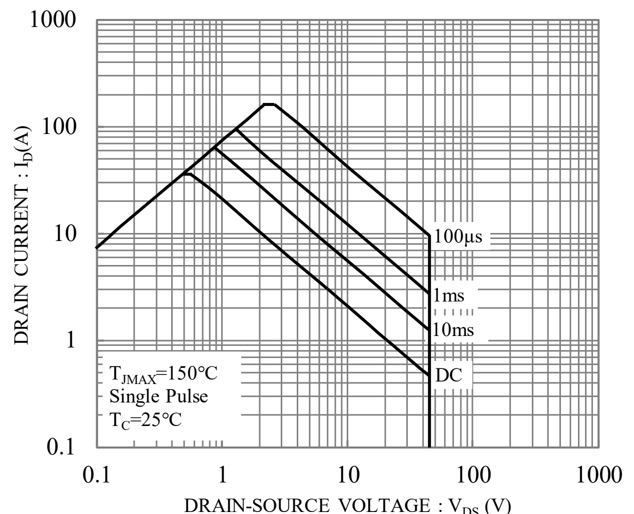


Fig.12 Safe Operation Area

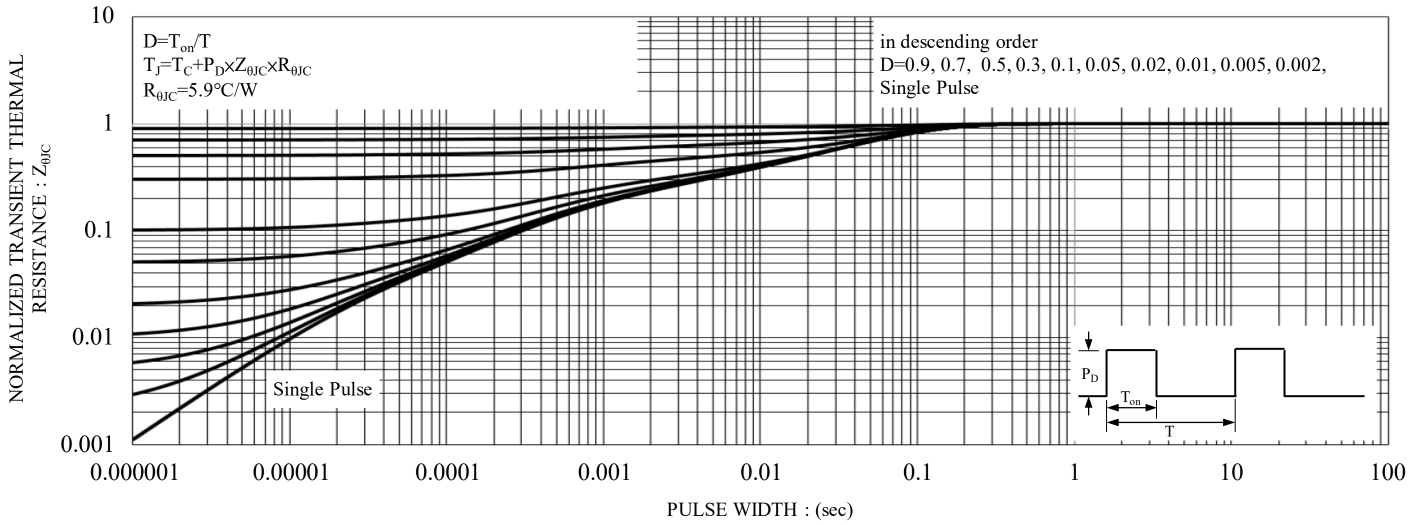


Fig.13 Maximum Transient Thermal Impedance

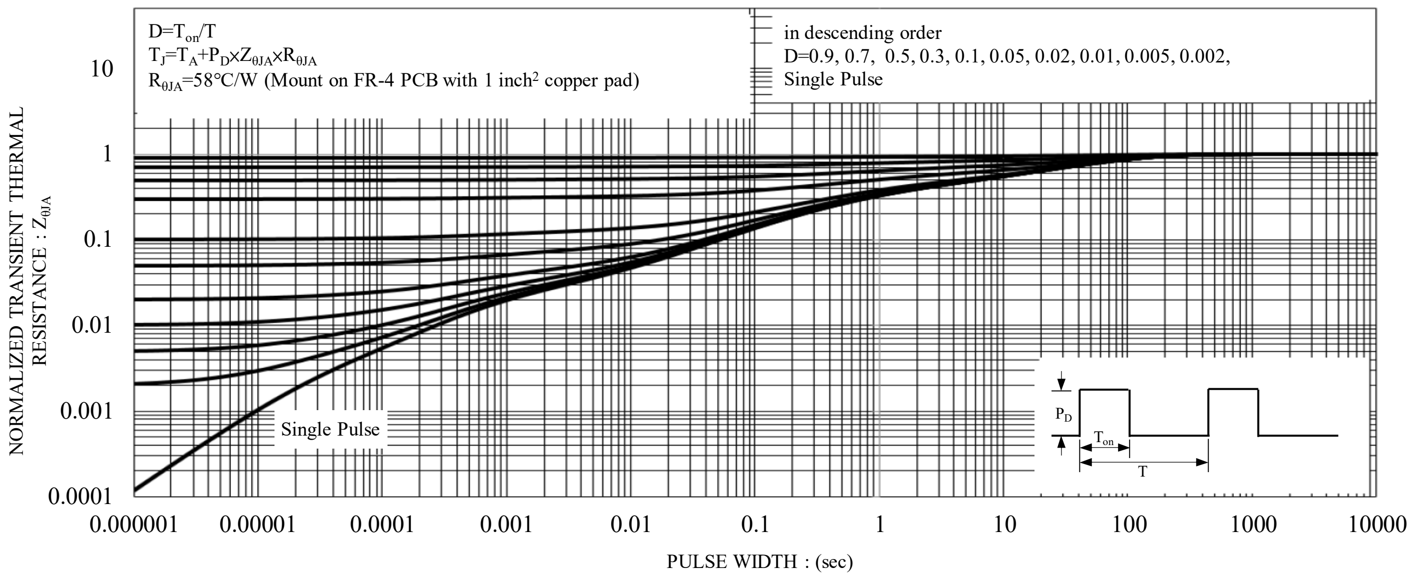
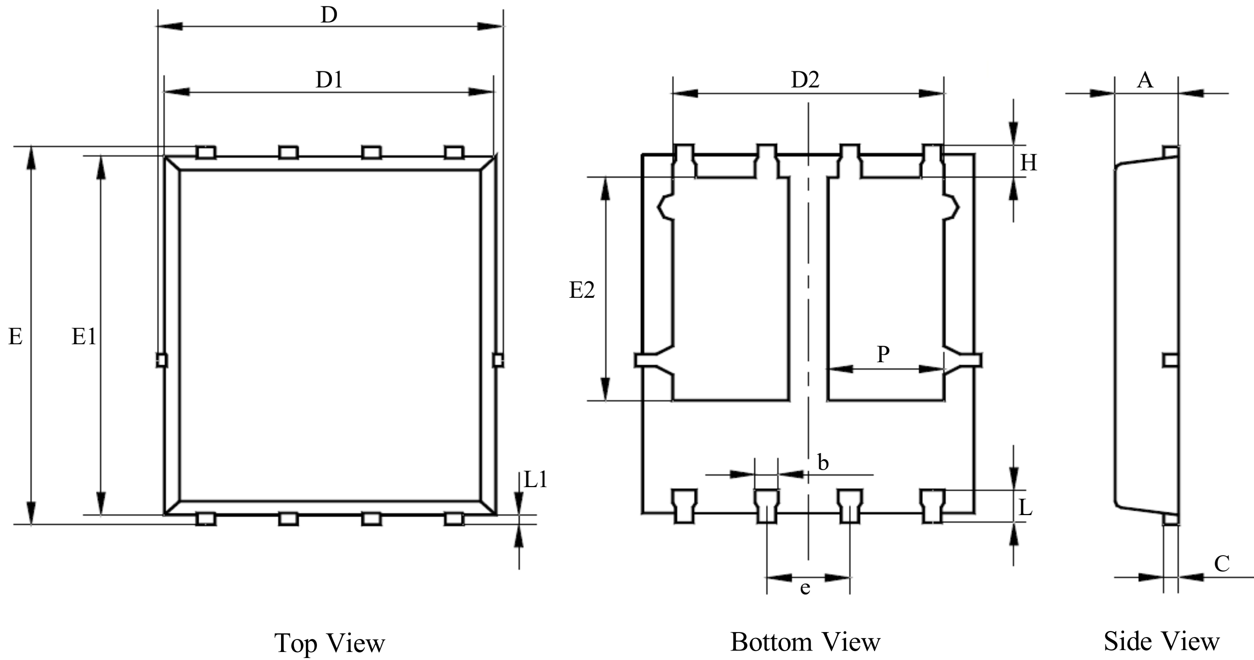


Fig.14 Maximum Transient Thermal Impedance

PACKAGE DIMENSION

DFN5×6-8L



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.90	1.12	0.035	0.044
b	0.33	0.51	0.013	0.020
C	0.11	0.34	0.004	0.013
D	4.70	5.26	0.185	0.207
D1	4.70	5.10	0.185	0.201
D2	3.56	4.50	0.140	0.177
E	5.75	6.25	0.226	0.246
E1	5.60	6.00	0.220	0.236
E2	3.18	3.66	0.125	0.144
e	1.17	1.37	0.046	0.054
L	0.35	0.71	0.014	0.028
L1	0.06	0.20	0.002	0.008
H	0.35	0.71	0.014	0.028
P	1.70	2.30	0.067	0.091

SUGGESTED SOLDER PAD LAYOUT